

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	"2003052404"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:37
L2	2	"20030052404"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:37
L3	204684	((flipchip (flip adj chip) ((semiconductor die chip ic (integrated adj circuit) element) with (bga c4 bump ball)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:53
L4	1341028	(carrier substrate board pcb) with (via hole through throughhole opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:54
L5	223241	4 with (trace wiring conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:55
L6	12449	5 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:55
L7	1371768	(carrier substrate board pcb) with (via cavit\$4 hole through throughhole opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:56
L8	227131	7 with (trace wiring conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:56
L9	12698	8 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:57

L10	1670	9 same (anchor\$4 within embed\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:57
L11	1601	(electrode contact pad terminal) and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/12 15:58

4/12/08 4:13:29 PM

C:\Documents and Settings\AWilliams\My Documents\EAST\Workspaces\10339834.wsp